Chips Act 2.0 and International Collaboration

Semicon Europe, Building Europe's Trusted Semiconductor Alliances

Munich, 10 November 2026

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Microelectronics and Photonics

DG CNECT, European Commission

European Commission

Chips Act in force since September 2023

European Semiconductor Board (Governance)

Pillar I

Chips for Europe Initiative

- **Aim**: bolster large-scale technological capacity building and innovation within the EU semiconductor ecosystem.
- **Actions**: set up of pilot lines, competence centres, design platform, Chips Fund

Pillar II

Security of Supply

- **Aim**: attract investments to increase semiconductor manufacturing capacity, contributing to security of supply.
- **Actions**: EUR 80 billion committed in manufacturing

Pillar III

Monitoring and Crisis Response

- **Aim:** monitoring the supply chain, coordinate actions with Member States, especially in times of crises.
- **Actions:** monitoring and alerting system, European Semiconductor Board.

Mandatory evaluation & review by September 2026

Research policy + **Industry policy** + **Crisis management**

Chips JU

FOAK Investments

IPCEI Microelectronics and Communication Technologies

European Semiconductor Board

Pillar I – Chips for Europe Initiative

Infrastructures open to a wide range of EU Users

5 operational

Pilot lines

Prototyping of validated designs
Testing of equipment
Validation of process flows



Competence centres

Access to technical expertise
Helping companies to approach and improve design capabilities and developing skills

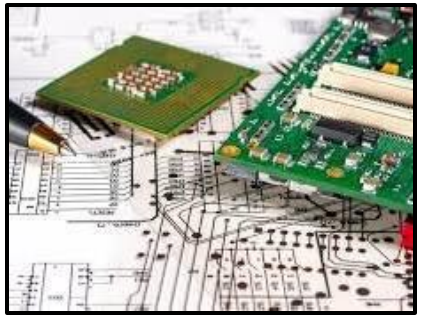


28 countries

Launched last week

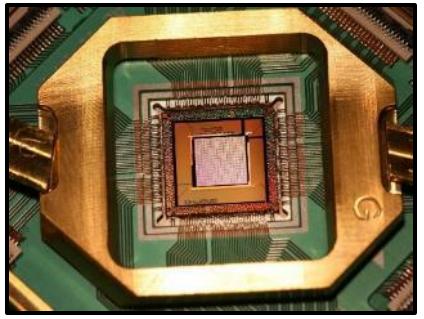
Design Platform

Help designing semiconductor devices, via access to Electronic Design Automation tools and IP libraries



Quantum chips

Technology and engineering capacities for accelerating innovative development of quantum chips



In progress

➢ **More than 90% of budget has been committed already (~ EUR 3 billion)**

Pillar II – Security of supply and resilience

State aid for production facilities

Company	Location	Technology
STMicroelectronics	Catania, Italy	*SiC Wafer*
STMicro & GlobalFoundries	Crolles, France	*300-mm FD-SOI*
STMicroelectronics	Catania, Italy	*SiC Devices*
ESMC	Dresden, Germany	*CMOS, FinFET*
Silicon Box	Novara, Italy	*Advanced Packaging*
Infineon	Dresden, Germany	*Discrete, Analog/Mixed Signals*
ams OSRAM	Premstätten, Austria	*CMOS*
Ephos	Milan, Italy	*Glass-based Photonic Chips*
Onsemi	Rožnov, Czech Republic	*SiC Devices*
GlobalFoundries	Dresden, Germany	*300-mm FD-SOI and BCD*
X-Fab	Erfurt, Germany	*Advanced Packaging*
Zadient	Bitterfeld, Germany	*SiC source granulate material*
Carl Zeiss	Oberkochen, Germany	*EUV lithography optics*
QuantumDiamonds	Munich, Germany	*Quantum-based metrology*
Element 3-5	Baesweiler, Germany	*SiC epitaxial wafers*
Vishay	Itzehoe, Germany	*300mm Si power MOSFET*
KLA-Tencor	Weilburg, Germany	*Overlay, film metrology equipment*
KETEK	Munich, Germany	*X-ray detectors*
Infineon	Villach, Austria	*300mm power GaN*
Total	>33 billion Euros	

- Further, IPCEI ME-CT started in 2023 with around **EUR 20 billion** investments
- More projects in the pipeline

- **<u>Total EUR 52 billion EUR</u>** investment in productive capacities and **<u>46,000 jobs</u>** (direct and indirect) created.

Pillar III – Monitoring and crisis response

Strategic mapping of the semiconductor supply chain to anticipate and mitigate shortages

Strengthening the EU and Member States' **abilities to react to crises** related to disruptions of the semiconductor supply chain

Emergency Toolbox

1. **Information gathering**
2. **Priority rated orders**
3. **Common purchasing**
4. **Export control**

Pillar III work strands:

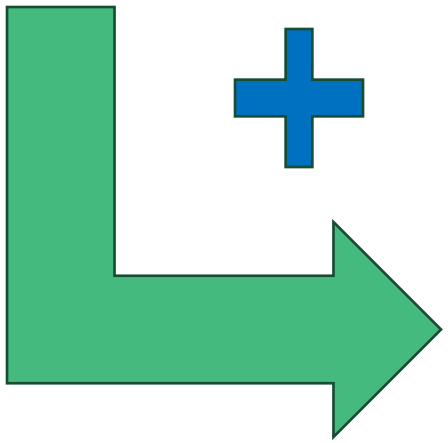
- **Established the European Semiconductor Board (ESB)**
- **Established the SCAN monitoring system, semiconductor alert system and monthly reporting to the ESB**
- **Developed analysis of supply chains**, choke points, dependencies as part of the strategic mapping
- **Perform** a mapping of Key Market Actors with Member States
- **Developed** crisis management procedures
- **Organising crisis management exercises** with the ESB and the Council to raise awareness and test the resilience of the supply chain

Chips Act 2.0

European Semiconductor Board

Pillar 1	*Pillar 2*	*Pillar 3*
Chips for Europe Initiative	**Security of Supply**	**Monitoring and Crisis Response**

From Chips Act 1…



…to Chips Act 2.0

Supply-side measures

- Clarify scope of *First of a Kind*
- Fast-track permitting
- Strategic Projects
- Lab-to-fab accelerators
- Semiconductor Regions of Excellence

Demand-side measures

- Innovation procurement
- Demand Accelerators & Forum
- Grand Challenges
- Innovation procurement

Supply chain resilience measures

- B2B Semiconductor Supply Chain Platform
- Information requests

Improving framework conditions

- RDI support
- Increased focus on skills

International engagements

- **International cooperation on semiconductors**
  - To increase resilience and diversification of supply chains
  - Includes early warning mechanisms, exchanges on subsidies, research, and more…
- **Trade and Technology Councils (TTC)** with US and India 
- **Digital Partnerships** with Japan, Korea, Singapore, and Canada 
- **Multilateral engagement:** G7, OECD, GAMS, Pax Silica 





- **Chips Act 2.0**
  - **Strategic Partnerships:** mutual commitment between Union and partners to improve security of supply and cooperation along semiconductor value chain
  - **Domestic Undertakings**: includes entities owned/controlled by entities in Strategic Partnership countries

Thank you

European Commission